



# SOT339-1

plastic shrink small outline package; 20 leads; body width 5.3 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SSOP20
<b>Package type industry code</b>	SSOP20
<b>Package style descriptive code</b>	SSOP (shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-150
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-2-2003

Table 1. Package summary

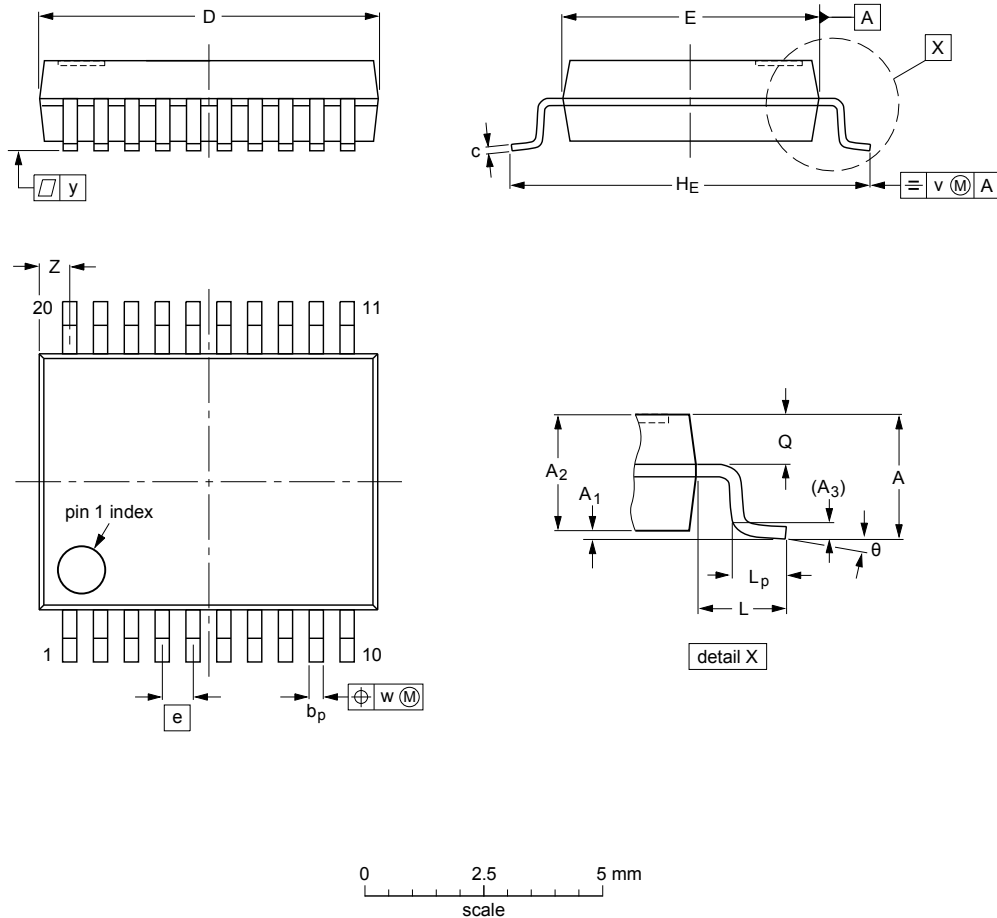
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7	-	7.2	7.4	mm
E	package width	5.2	-	5.3	5.4	mm
A	seated height	[tbd]	-	2	2	mm
A <sub>2</sub>	package height	1.65	-	1.73	1.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	



2. Package outline

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT339-1		MO-150				99-12-27 03-02-19

Fig. 1. Package outline SSOP20 (SOT339-1)

### 3. Soldering

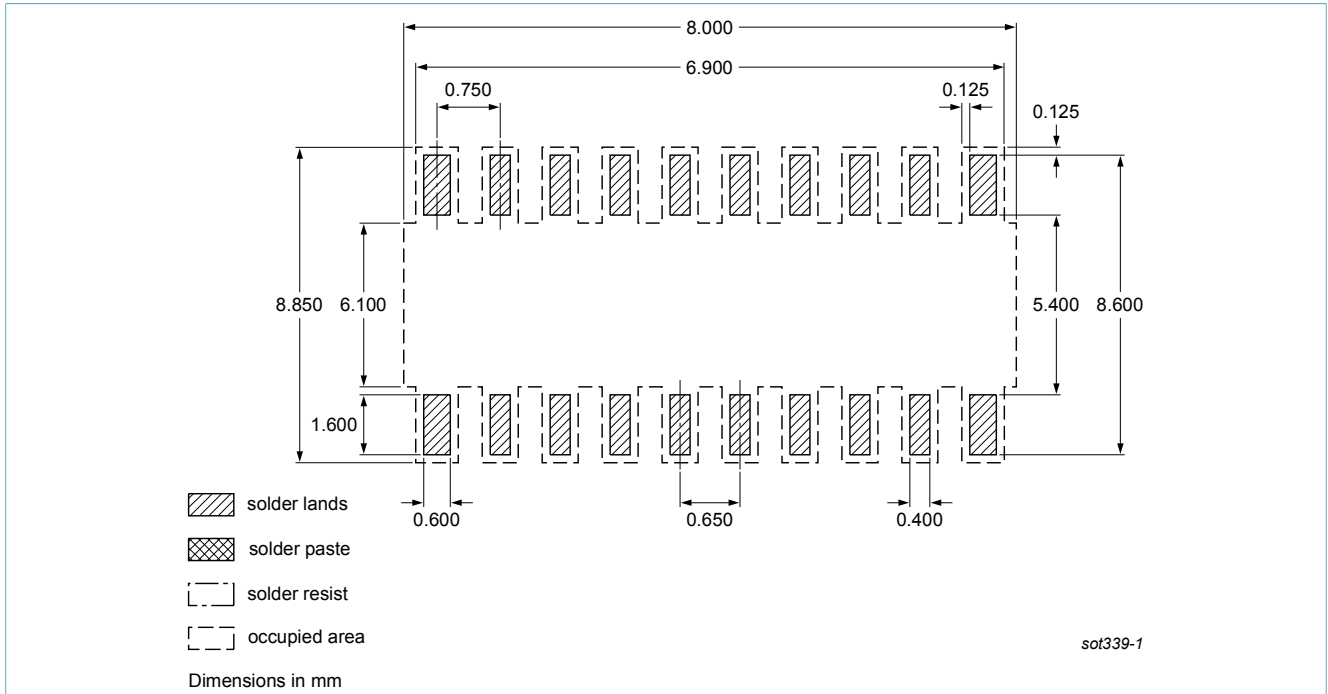


Fig. 2. Reflow soldering footprint for SSOP20 (SOT339-1)

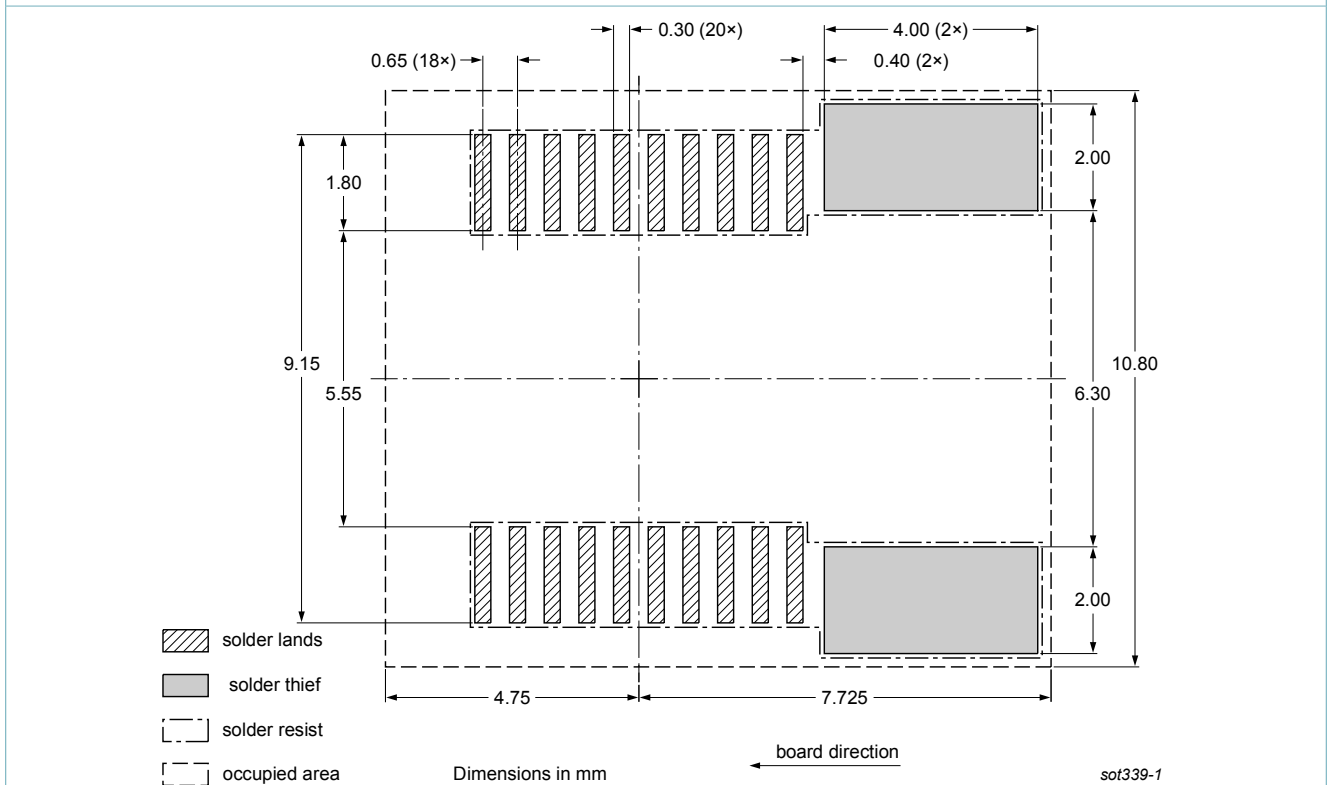


Fig. 3. Wave soldering footprint for SSOP20 (SOT339-1)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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